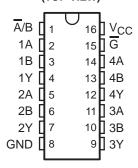
SN54HC158, SN74HC158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS296D - JANUARY 1996 - REVISED OCTOBER 2003

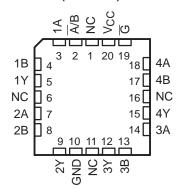
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}

SN54HC158 . . . J OR W PACKAGE SN74HC158 . . . D, N, NS, OR PW PACKAGE (TOP VIEW)



- Typical t_{pd} = 11 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max

SN54HC158...FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These data selectors/multiplexers contain inverters and drivers that supply full data selection to the four output gates. A separate strobe (\overline{G}) input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 'HC158 devices' outputs provide inverted data.

ORDERING INFORMATION

TA	PACKA	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC158N	SN74HC158N
		Tube of 40	SN74HC158D	
	SOIC - D	Reel of 2500	SN74HC158DR	HC158
–40°C to 85°C		Reel of 250	SN74HC158DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC158NSR	HC158
		Tube of 90	SN74HC158PW	
	TSSOP - PW	Reel of 2000	SN74HC158PWR	HC158
		Reel of 250	SN74HC158PWT	
	CDIP – J	Tube of 25	SNJ54HC158J	SNJ54HC158J
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HC158W	SNJ54HC158W
	LCCC – FK	Tube of 55	SNJ54HC158FK	SNJ54HC158FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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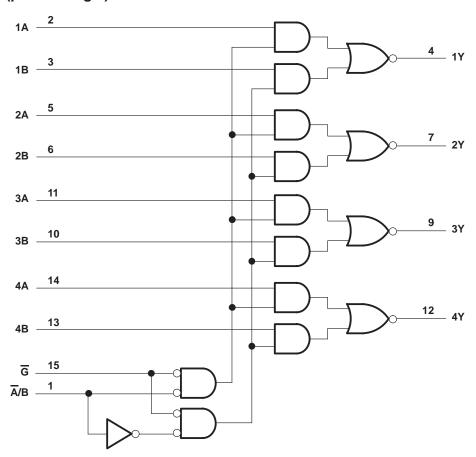


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FUNCTION TABLE

	INPU	ΓS		
IG	SELECT	DA	TΑ	OUTPUT
9	A/B	Α	В	·
Н	Х	Х	Х	Н
L	L	L	X	Н
L	L	Н	X	L
L	Н	Χ	L	Н
L	Н	Χ	Н	L

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, PW, and W packages.

SN54HC158, SN74HC158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5	V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)		$\pm 20 \ mA$
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	C) (see Note 1)		$\pm 20 \ mA$
Continuous output current, I_O ($V_O = 0$ to V_{CC})			$\pm 35~\text{mA}$
Continuous current through V _{CC} or GND			$\pm 70~\text{mA}$
Package thermal impedance, θ _{JA} (see Note 2)	: D package		73°C/W
	N package		67°C/W
	NS package		64°C/W
	PW package	1	.08°C/W
Storage temperature range, T _{sta}		. −65°C t	o 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	I54HC15	8	SN	174HC15	8	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15		7	3.15			V
		VCC = 6 V	4.2		\C.V.	4.2			
		V _{CC} = 2 V		PAL	0.5			0.5	
VIL	Low-level input voltage	V _{CC} = 4.5 V		2	1.35			1.35	V
		V _{CC} = 6 V		Ç,	1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN54HC158, SN74HC158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54H	C158	SN74H	IC158	
PARAMETER	TEST CO	ONDITIONS	IS V _{CC}		TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VOH VI = VIH or VIL		6 V	5.9	5.999		5.9	4	5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7	151	3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	KI	5.34		
			2 V		0.002	0.1		0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1	Ό,	0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1	¹ QC	0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.17	0.26	d'a	0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26	,	0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	\ \	T,	ղ = 25°C	;	SN54HC158	SN74HC158	LINUT																						
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT																						
			2 V		63	125	190	160																							
A or B	A or B	Y	4.5 V		13	25	38	32																							
			6 V		11	21	32	27																							
	Ā/B	Y	2 V		67	125	190	160																							
t _{pd}			4.5 V		18	25	38	31	ns																						
			6 V		14	21	32	27																							
			2 V		59	115	170	145																							
	G	Υ	4.5 V		16	23	34	29																							
			6 V		13	20	29	25																							
			2 V		28	60	90	75																							
t _t		Y	Y	Y	Y	Y	Y	Y	Υ	Y	Y	Y	Y	Υ	Υ	Y	Y	Y	Y	Υ	Y	Y	Y	Υ	4.5 V		8	12	18	15	ns
-			6 V		6	10	15	13																							

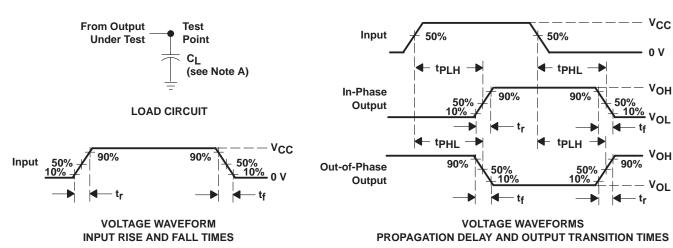
switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

212115	FROM	то	.,	T,	4 = 25°C	;	SN54H	C158	SN74H	C158							
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT						
			2 V		81	190		290		235							
	A or B	Y	4.5 V		23	38		58		47							
			6 V		18	33		49		41							
		Y		2 V		81	210		320		260						
t _{pd}			4.5 V		23	42	40	64		52	ns						
·			6 V		18	36	4:	54		45							
		Y	2 V		91	190	37/	290		235							
	G		Υ	Υ	Υ	Υ	Υ	Y	Υ	4.5 V		24	38	0	58		47
			6 V		18	33	ď	49		41							
			2 V		45	210		315		265							
t _t	Y	Y	Y	Y	Y	4.5 V		17	42		63		53	ns			
			6 V		13	36		53		45							

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power	dissipation capacitance	No load	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_0 = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
	(1)		J			(2)	(6)	(0)		(40)	
SN74HC158D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158	Samples
SN74HC158DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158	Samples
SN74HC158DT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158	Samples
SN74HC158DTG4	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158	Samples
SN74HC158N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC158N	Samples
SN74HC158NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC158N	Samples
SN74HC158NSR	ACTIVE	so	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158	Samples
SN74HC158PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158	Samples
SN74HC158PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC158	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

10-Dec-2020

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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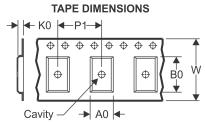
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	
Γ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

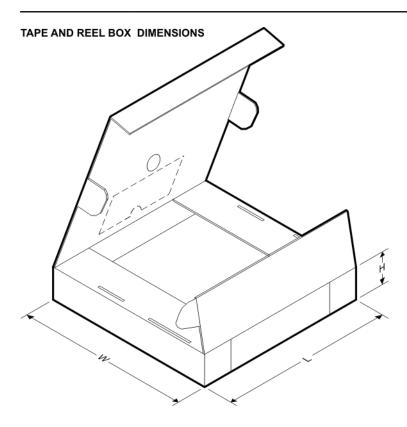


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC158DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC158NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC158PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC158DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC158NSR	SO	NS	16	2000	853.0	449.0	35.0
SN74HC158PWR	TSSOP	PW	16	2000	853.0	449.0	35.0

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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